

In the Claims:

1. (Currently Amended) A die bonder which mounts on a base, piece by piece, dies, each having a surface on which a semiconductor device is formed, the die bonder comprising:  
a laser machining part which causes laser light to become incident from a surface of a wafer before dividing into individual dies so that the laser light forms a modified region within the wafer,  
wherein the wafer is divided into individual dies in the laser machining part; and,  
an expanding part that widens a gap between the individual dies after the laser light forms the modified region within the wafer, said expanding part comprising an expanding stage having a frame with a chamfered top edge portion which engages an expandable wafer tape on which the wafer is supported.
2. (Original) The die bonder as defined in claim 1, wherein a product type marking is provided on a surface of the die by the laser machining part.
3. (Original) The die bonder as defined in claim 1, wherein all dies on the wafer are divided into the individual dies by the laser machining part.
4. (Original) The die bonder as defined in claim 3, wherein a product type marking is provided on a surface of the die by the laser machining part.
5. (Original) The die bonder as defined in claim 1, wherein only conforming dies on the wafer are divided into the individual dies by the laser machining part.
6. (Original) The die bonder as defined in claim 5, wherein a product type marking is provided on a surface of the die by the laser machining part.
7. (Currently Amended) The die bonder as defined in claim 1, wherein the expanding part includes an expanding stage that supports the wafer during application of the

laser light and supports the wafer during pickup of the individual dies for mounting on the base.

8. (Currently Amended) The die bonder as defined in claim 7, wherein the expanding part further includes an expandable wafer tape is mounted on [[a]] said frame, and wherein the expandable wafer tape is positioned on the expanding stage.

9. (Previously Presented) The die bonder as defined in claim 8, wherein the expanding part further includes a frame pusher that moves the frame relative to the expanding stage to cause the expandable wafer tape to expand and widen the gap between the individual dies.

10. (Canceled)

11. (Previously Presented) The die bonder as defined in claim 1, further comprising a pushup device that cooperates with the expanding part to selectively push up an individual die.

12. (Previously Presented) The die bonder as defined in claim 11, wherein the pushup device includes a movable needle.

13. (Previously Presented) The die bonder as defined in claim 11, further comprising a bonding part that includes a collet that picks up the individual die that is pushed up by the pushup device.

14. (Previously Presented) The die bonder as defined in claim 1, further comprising a bonding part that includes a collet that selectively holds an individual die for mounting on the base.

15. (Previously Presented) The die bonder as defined in claim 14, wherein the collet holds the individual die by suction.